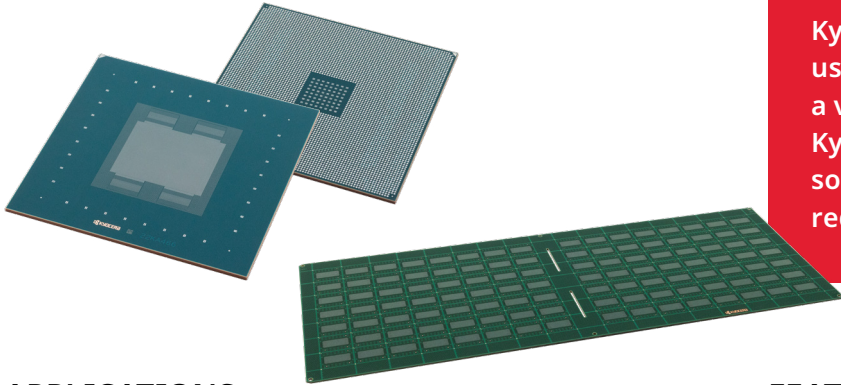


PACKAGE SUBSTRATE SOLUTIONS FCBGA TECHNOLOGY



Kyocera provides package substrates by using organic products that are ideal for a variety of applications. Kyocera FCBGA organic substrate solutions meet increasing customer requirements.

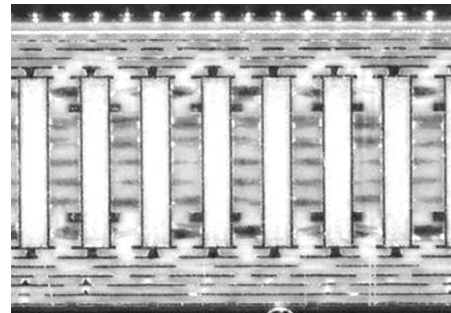
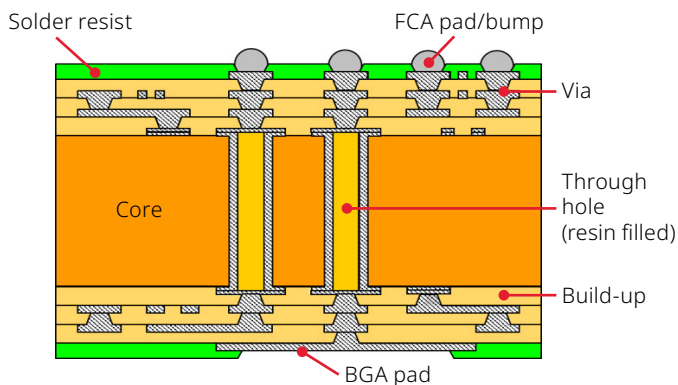
APPLICATIONS

- ▶ Processing unit packages e.g.:
 - ▶ CPU for servers
 - ▶ ASIC for networks
 - ▶ SoC for automobiles

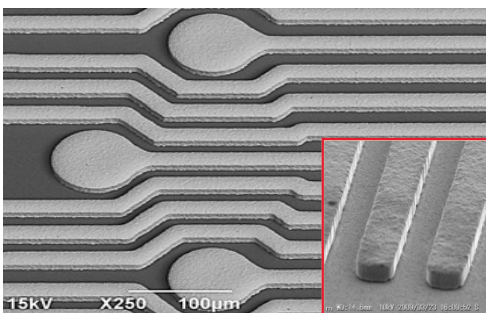
FEATURES

- ▶ Large body size (~ 120 mm SQ)
- ▶ High layer count (up to 10L/side build-up)
- ▶ Fine pattern L/S 9/12 μm
- ▶ Impedance control characteristic
- ▶ Applicable for low Df build-up materials
- ▶ Pb-free / Halogen-free materials

CROSS SECTION IMAGE



ADVANCED TECHNOLOGY



L/S 9/12 μm

- ▶ Fine pitch bumping (~ 110 μm)
- ▶ Fine pattern L/S 9/12 μm (now) L/S 8/8 (CY24)
- ▶ Lower CTE / high modulus core
- ▶ Multi-layer core technology

ENHANCED THIN CORE (ETC) FCBGA TECHNOLOGY

ADVANTAGES

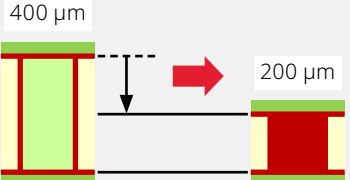
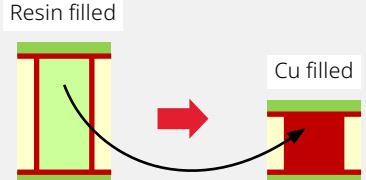
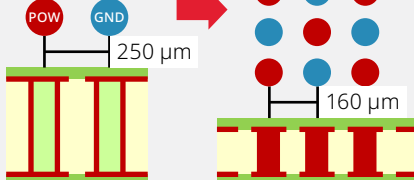
- ▶ **Electrical performance improvement** due to reduced core thickness and Cu filled vias
 - Self inductance improvement
 - DC resistance improvement
- ▶ **Higher integration thanks to advanced design rules**
 - Smaller drill/hole size due to thin core
 - higher amount of holes possible
 - Fine pattern on core
- ▶ **Less layer count** (and/or smaller body size)
 - Design to cost
 - Improved manufacturing lead time

Kyocera's "ETC-FCBGA" uses low CTE thin core technology with laser through holes to provide increased performance.

FEATURES

- ▶ High layer count (up to 6L/side build-up)
- ▶ Fine pattern on core layer by MSAP
- ▶ Fine pattern L/S 9/12 μm
- ▶ Fine pitch TH (~160 μm)
- ▶ Capable for strip / singulated form

ELECTRICAL PERFORMANCE

<p>▶ Thin core → Self inductance improvement → DC resistance improvement</p> 	<p>▶ Cu filled through hole → DC resistance improvement</p> 	<p>▶ Fine pitch through holes → Mutual inductance improvement</p> 
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CROSS SECTION IMAGE

